



Description

The GM76FV1664 / GM76FU1664 / GM76FQ1664 / GM76FE1664 / GM76FS1664 is a 1,048,576 bits static random access memory organized as 65,536 words by 16 bits. Using a full CMOS technology and it provides high speed operation with minimum cycle time of 70/85ns. The device is placed in a low power standby mode with /CS high and the output enable (/OE) allows fast memory access. Thus it is suitable for high speed and low power applications, especially where battery back-up is required.

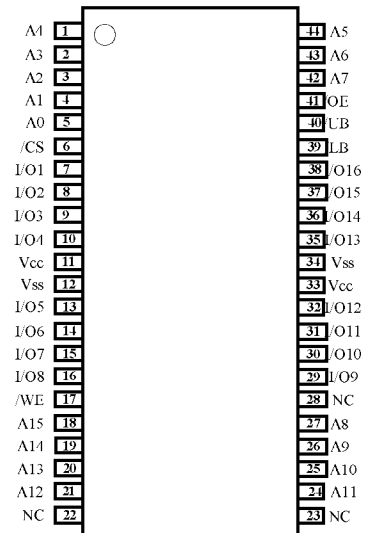
Features

- Organization: 64Kx16
- Data Byte Control : /LB = I/O1~I/O8, /UB = I/O9~I/O16
- Power Supply /Speed
 - GM76FV1664 : 3.3V ± 0.3V / 70/85ns
 - GM76FU1664 : 3.0V ± 0.3V / 70/85ns
 - GM76FQ1664 : 2.5V ± 0.3V / 85/100ns
 - GM76FE1664 : 2.0V ± 0.2V / 100/120ns
 - GM76FS1664 : 1.8V ± 0.2V / 120/150ns
- Low Power Standby
 - 5uA(LL)/1uA(SL)
- Low Data Retention Voltage: 1.5V(Min)
- TTL compatible inputs and outputs
- Package Type : JEDEC Standard 44-TSOP(II)
- Temperature Range
 - Commercial(0 ~ 70 °C)
 - Industrial(-40 ~ 85 °C)

Pin Description

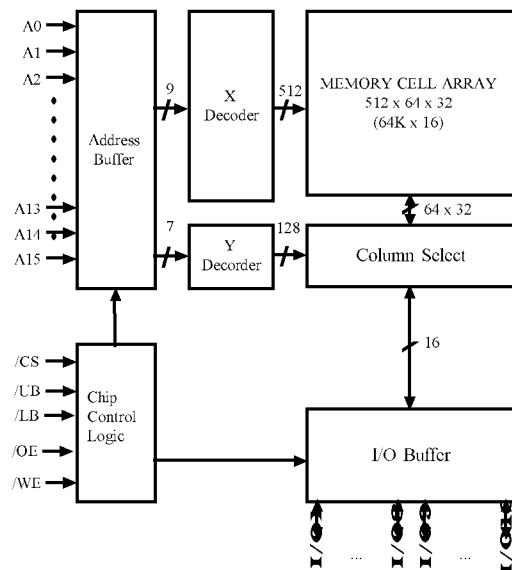
Pin	Function
A0-A15	Address Inputs
/WE	Write Enable Input
/CS	Chip Select Input
/OE	Output Enable Input
I/O1-I/O16	Data Inputs/Outputs
/LB	Lower Byte(I/O1~I/O8)
/UB	Upper Byte(I/O9~I/O16)
Vcc	Power Supply (1.6V ~3.6V)
Vss	Ground
NC	No Connection

Pin Configuration



(Top View)

Block Diagram



PRELIMINARY

GM76FV1664,GM76FU1664,GM76FQ1664,GM76FE1664,GM76FS1664

Absolute Maximum Ratings*

Symbol	Parameter		Rating	Unit
T _A	Ambient Temperature under Bias	GM76FV1664 GM76FU1664 GM76FQ1664 GM76FE1664 GM76FS1664	0 ~ 70	°C
		GM76FV1664-I GM76FU1664-I GM76FQ1664-I GM76FE1664-I GM76FS1664-I	-40 ~ 85	°C
T _{STG}	Storage Temperature		-55 ~ 150	°C
T _{SOL}	Soldering Temperature and Time		260, 5 (at lead)	°C, S
V _{CC}	Supply Voltage		-0.2 ~ 4.6V	V
V _{IN}	Input Voltage		-0.2 ~ 3.9V	V
V _{I/O}	Input and Output Voltage		-0.2 ~ 3.9V	V

*: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended DC Operating Conditions (T_A = - 40 ~ 85 °C)

Symbol	Parameter	Product	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	GM76FV1664-(I)	3.0	3.3	3.6	V
		GM76FU1664-(I)	2.7	3.0	3.3	
		GM76FQ1664-(I)	2.2	2.5	2.8	
		GM76FE1664-(I)	1.8	2.0	2.2	
		GM76FS1664-(I)	1.6	1.8	2.0	
V _{IH}	Input High Voltage	GM76FV1664-(I)	2.2	-	V _{CC} + 0.2	V
		GM76FU1664-(I)	2.2			
		GM76FQ1664-(I)	2.0			
		GM76FE1664-(I)	1.6			
		GM76FS1664-(I)	1.4			
V _{IL}	Input Low Voltage	All Family	-0.2*	-	0.4	V

*Note : V_{IL}(min) = -1.5V for ≤ 30ns pulse

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Truth Table

/CS	/OE	/WE	/LB	/UB	I/O1 ~ I/O8	I/O9 ~ I/O16	Vcc Current
H	X	X	X	X	Not Selected	Not Selected	Iccs1, Iccs2
L	L	H	L	L	Read	Read	Icc, Icc1, Icc2
			L	H	Read	High - Z	Icc, Icc1, Icc2
			H	L	High - Z	Read	Icc, Icc1, Icc2
L	X	L	L	L	Write	Write	Icc, Icc1, Icc2
			L	H	Write	Not Write/High - Z	Icc, Icc1, Icc2
			H	L	Not Write/High - Z	Write	Icc, Icc1, Icc2
L	H	H	X	X	High - Z	High - Z	Icc, Icc1, Icc2
L	X	X	H	H	High - Z	High - Z	Icc, Icc1, Icc2

*Note: X means don't care

Capacitance (f = 1MHz, T_A = 25°C)

Symbol	Parameter	Test Conditions	Min	Max	Unit
C _{IN}	Input Capacitance	V _I = 0V	-	6	pF
C _{IO}	Output Capacitance	V _O = 0V	-	8	pF

*Note: This parameter is sampled and not 100% tested.

AC Operating Characteristics

Test Conditions (T_A = - 40 ~ 85°C, unless otherwise noted.)

Parameter	Value
Input Pulse Level	0.4 to 2.2V for Vcc=3.3V,3.0V,2.5V 0.4 to 1.8V for Vcc=2.0V 0.4 to 1.6V for Vcc=1.8V
Input Rise and Fall Time	5ns
Input and Output Timing Reference Levels	1.5V for Vcc=3.3V,3.0V 1.1V for Vcc=2.5V 0.9V for Vcc=2.0V 0.8V for Vcc=1.8V
Output Load	C _L = 30 pF + 1TTL Load

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DC and Operating Characteristics ($T_A = -40 \sim 85^\circ\text{C}$)

Symbol	Parameter	Conditions	Min	*Typ	Max	Unit	
$I_{i(L)}$	Input Leakage Current	$V_{IN} = V_{SS} \text{ to } V_{CC}$	-1	-	1	μA	
$I_{o(L)}$	Output Leakage Current	$/CS = V_{IH}$ or $/UB = V_{IH}$ or $/LB = V_{IH}$ or $/OE = V_{IH}$ or $/WE = V_{IL}$ $V_{SS} \leq V_{IO} \leq V_{CC}$	-1	-	1	μA	
V_{OH}	High Level Output Voltage	I_{OH} -1.0mA at $V_{CC} = 3.0/3.3\text{V}$ -0.5mA at $V_{CC} = 2.5\text{V}$ -0.44mA at $V_{CC} = 2.0\text{V}$ -0.44mA at $V_{CC} = 1.8\text{V}$	2.4 2.0 1.6 1.4	-	-	V	
V_{OL}	Low Level Output Voltage	I_{OL} 2.1mA at $V_{CC} = 3.0/3.3\text{V}$ 0.5mA at $V_{CC} = 2.5\text{V}$ 0.33mA at $V_{CC} = 2.0\text{V}$ 0.26mA at $V_{CC} = 1.8\text{V}$	-	-	0.4	V	
I_{CC}	Operating Supply Current	$/CS = V_{IL}$ $V_{IN} = V_{IH}$ or V_{IL} , $I_{OUT} = 0\text{mA}$	-	-	5.0	mA	
I_{CC1}	Average Operating Current	$/CS = V_{IL}$ $V_{IN} = V_{IH}$ or V_{IL} $I_{OUT} = 0\text{mA}$ tcycle = Min	$V_{CC} = 3.0/3.3\text{V}$ $V_{CC} = 2.5\text{V}$ $V_{CC} = 2.0\text{V}$ $V_{CC} = 1.8\text{V}$	-	-	80 60 40 35	mA
I_{CC2}		$/CS = 0.2\text{V}$ $V_{IN} = V_{CC} - 0.2\text{V}/0.2\text{V}$ $I_{OUT} = 0\text{mA}$ tcycle = 1 μs	-	-	10	mA	
I_{CCS1}	Standby Current (TTL)	$/CS = V_{IH}$	$V_{CC} = 3.0/3.3\text{V}$ $V_{CC} = 2.5/2.0/1.8\text{V}$	-	-	0.5 0.3	mA
I_{CCS2}	Standby Current(CMOS)	$/CS = V_{CC} - 0.2\text{V}$	LL - Version SL - Version	- -	- -	5 1	μA

*Typ. Values are measured at 25°C

PRELIMINARY**GM76FV1664,GM76FU1664,GM76FQ1664,GM76FE1664,GM76FS1664****AC Operating Characteristics** ($V_{CC} = 3.3V \pm 0.3V$, $V_{CC} = 3.0V \pm 0.3V$)**Read Cycle** $T_A = -40 \sim 85^\circ C$

Symbol	Parameter	GM76FV1664-70 GM76FU1664-70		GM76FV1664-85 GM76FU1664-85		Unit
		Min	Max	Min	Max	
t_{RC}	Read cycle time	70	-	85	-	ns
t_{AA}	Address access time	-	70	-	85	ns
t_{CO}	Chip select access time (/CS)	-	70	-	85	ns
t_{BA}	Byte enable access time (/UB, /LB)	-	35	-	40	ns
t_{OE}	Output enable access time (/OE)	-	35	-	40	ns
t_{LZ}	Chip select to low - Z output (/CS)	10	-	10	-	ns
t_{OLZ}	Output enable to low - Z output (/OE)	5	-	5	-	ns
t_{BLZ}	Byte enable to low - Z output (/UB, /LB)	5	-	5	-	ns
t_{HZ}	Chip select to high - Z output (/CS)	-	25	-	30	ns
t_{OHZ}	Output enable to high - Z output (/OE)	-	25	-	30	ns
t_{BHZ}	Byte enable to high - Z output (/UB, /LB)	-	25	-	30	ns
t_{OH}	Output hold time	10	-	10	-	ns

Write Cycle

Symbol	Parameter	GM76FV1664-70 GM76FU1664-70		GM76FV1664-85 GM76FU1664-85		Unit
		Min	Max	Min	Max	
t_{WC}	Write cycle time	70	-	85	-	ns
t_{CW}	Chip select to end of write	65	-	70	-	ns
t_{BW}	Byte enable to end of write	65	-	70	-	ns
t_{AW}	Address valid to end of write	65	-	70	-	ns
t_{AS}	Address setup time	0	-	0	-	ns
t_{WP}	Write pulse width	50	-	60	-	ns
t_{WR}	Write recovery time	0	-	0	-	ns
t_{DW}	Data to write time overlap	30	-	35	-	ns
t_{DH}	Data hold from write time	0	-	0	-	ns
t_{WHZ}	Write to output in high - Z	-	25	-	30	ns
t_{OW}	Output active from end of write	5	-	5	-	ns

PRELIMINARY

GM76FV1664,GM76FU1664,GM76FQ1664,GM76FE1664,GM76FS1664

AC Operating Characteristics ($V_{CC} = 2.5V \pm 0.3V$, $T_A = -40 \sim 85^\circ C$)

Read Cycle

Symbol	Parameter	GM76FQ1664-85		GM76FQ1664-10		Unit
		Min	Max	Min	Max	
t _{RC}	Read cycle time	85	-	100	-	ns
t _{AA}	Address access time	-	85	-	100	ns
t _{CO}	Chip select access time (/CS)	-	85	-	100	ns
t _{BA}	Byte enable access time (/UB, /LB)	-	40	-	50	ns
t _{OE}	Output enable access time (/OE)	-	40	-	50	ns
t _{LZ}	Chip select to low - Z output (/CS)	10	-	15	-	ns
t _{OLZ}	Output enable to low - Z output (/OE)	5	-	5	-	ns
t _{BLZ}	Byte enable to low - Z output (/UB, /LB)	10	-	10	-	ns
t _{HZ}	Chip select to high - Z output (/CS)	-	30	-	30	ns
t _{OIZ}	Output enable to high - Z output (/OE)	-	30	-	30	ns
t _{BIZ}	Byte enable to high - Z output (/UB, /LB)	-	30	-	30	ns
t _{OH}	Output hold time	10	-	10	-	ns

Write Cycle

Symbol	Parameter	GM76FQ1664-85		GM76FQ1664-10		Unit
		Min	Max	Min	Max	
t _{WC}	Write cycle time	85	-	100	-	ns
t _{CW}	Chip select to end of write	70	-	80	-	ns
t _{BW}	Byte enable to end of write	70	-	80	-	ns
t _{AW}	Address valid to end of write	70	-	80	-	ns
t _{AS}	Address setup time	0	-	0	-	ns
t _{WP}	Write pulse width	60	-	75	-	ns
t _{WR}	Write recovery time	0	-	0	-	ns
t _{DW}	Data to write time overlap	35	-	45	-	ns
t _{DH}	Data hold from write time	0	-	0	-	ns
t _{WHZ}	Write to output in high - Z	-	30	-	35	ns
t _{OW}	Output active from end of write	5	-	5	-	ns

PRELIMINARY

GM76FV1664,GM76FU1664,GM76FQ1664,GM76FE1664,GM76FS1664

AC Operating Characteristics ($V_{CC} = 2.0V \pm 0.2V$, $T_A = -40 \sim 85^\circ C$)

Read Cycle

Symbol	Parameter	GM76FE1664-10		GM76FE1664-12		Unit
		Min	Max	Min	Max	
t _{RC}	Read cycle time	100	-	120	-	ns
t _{AA}	Address access time	-	100	-	120	ns
t _{CO}	Chip select access time (/CS)	-	100	-	120	ns
t _{BA}	Byte enable access time (/UB, /LB)	-	50	-	60	ns
t _{OE}	Output enable access time (/OE)	-	50	-	60	ns
t _{LZ}	Chip select to low - Z output (/CS)	20	-	20	-	ns
t _{OLZ}	Output enable to low - Z output (/OE)	5	-	10	-	ns
t _{BLZ}	Byte enable to low - Z output (/UB, /LB)	10	-	10	-	ns
t _{HZ}	Chip select to high - Z output (/CS)	-	30	-	40	ns
t _{OIZ}	Output enable to high - Z output (/OE)	-	30	-	40	ns
t _{BIZ}	Byte enable to high - Z output (/UB, /LB)	-	30	-	40	ns
t _{OH}	Output hold time	15	-	15	-	ns

Write Cycle

Symbol	Parameter	GM76FE1664-10		GM76FE1664-12		Unit
		Min	Max	Min	Max	
t _{WC}	Write cycle time	100	-	120	-	ns
t _{EW}	Chip select to end of write	80	-	100	-	ns
t _{BW}	Byte enable to end of write	80	-	100	-	ns
t _{AW}	Address valid to end of write	80	-	100	-	ns
t _{AS}	Address setup time	0	-	0	-	ns
t _{WP}	Write pulse width	75	-	85	-	ns
t _{WR}	Write recovery time	0	-	0	-	ns
t _{DW}	Data to write time overlap	45	-	50	-	ns
t _{DH}	Data hold from write time	0	-	0	-	ns
t _{WHZ}	Write to output in high - Z	-	35	-	40	ns
t _{OW}	Output active from end of write	5	-	5	-	ns

PRELIMINARY

GM76FV1664,GM76FU1664,GM76FQ1664,GM76FE1664,GM76FS1664

AC Operating Characteristics ($V_{CC} = 2.0V \pm 0.2V$, $T_A = -40 \sim 85^\circ C$)

Read Cycle

Symbol	Parameter	GM76FS1664-12		GM76FS1664-15		Unit
		Min	Max	Min	Max	
t _{RC}	Read cycle time	120	-	150	-	ns
t _{AA}	Address access time	-	120	-	150	ns
t _{CO}	Chip select access time (/CS)	-	120	-	150	ns
t _{BA}	Byte enable access time (/UB, /LB)	-	60	-	75	ns
t _{OE}	Output enable access time (/OE)	-	60	-	75	ns
t _{LZ}	Chip select to low - Z output (/CS)	20	-	20	-	ns
t _{OLZ}	Output enable to low - Z output (/OE)	10	-	10	-	ns
t _{BLZ}	Byte enable to low - Z output (/UB, /LB)	10	-	10	-	ns
t _{HZ}	Chip select to high - Z output (/CS)	-	40	-	50	ns
t _{OHZ}	Output enable to high - Z output (/OE)	-	40	-	50	ns
t _{BHZ}	Byte enable to high - Z output (/UB, /LB)	-	40	-	50	ns
t _{OH}	Output hold time	15	-	15	-	ns

Write Cycle

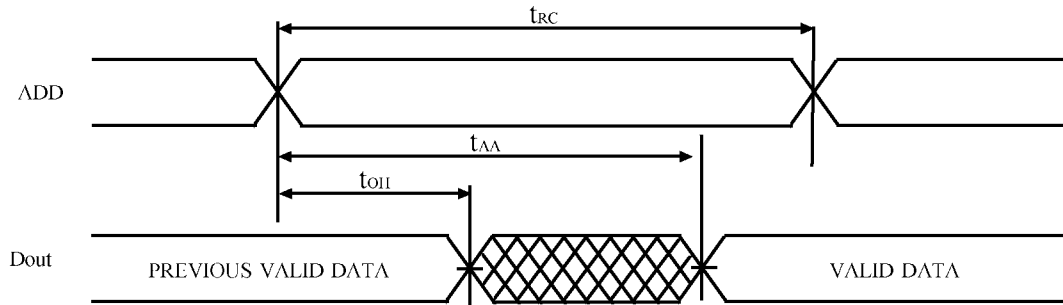
Symbol	Parameter	GM76FS1664-12		GM76FS1664-15		Unit
		Min	Max	Min	Max	
t _{WC}	Write cycle time	120	-	150	-	ns
t _{CW}	Chip select to end of write	100	-	120	-	ns
t _{BW}	Byte enable to end of write	100	-	120	-	ns
t _{AW}	Address valid to end of write	100	-	120	-	ns
t _{AS}	Address setup time	0	-	0	-	ns
t _{WP}	Write pulse width	85	-	100	-	ns
t _{WR}	Write recovery time	0	-	0	-	ns
t _{DW}	Data to write time overlap	50	-	60	-	ns
t _{DH}	Data hold from write time	0	-	0	-	ns
t _{WHZ}	Write to output in high - Z	-	60	-	70	ns
t _{OW}	Output active from end of write	5	-	5	-	ns

PRELIMINARY

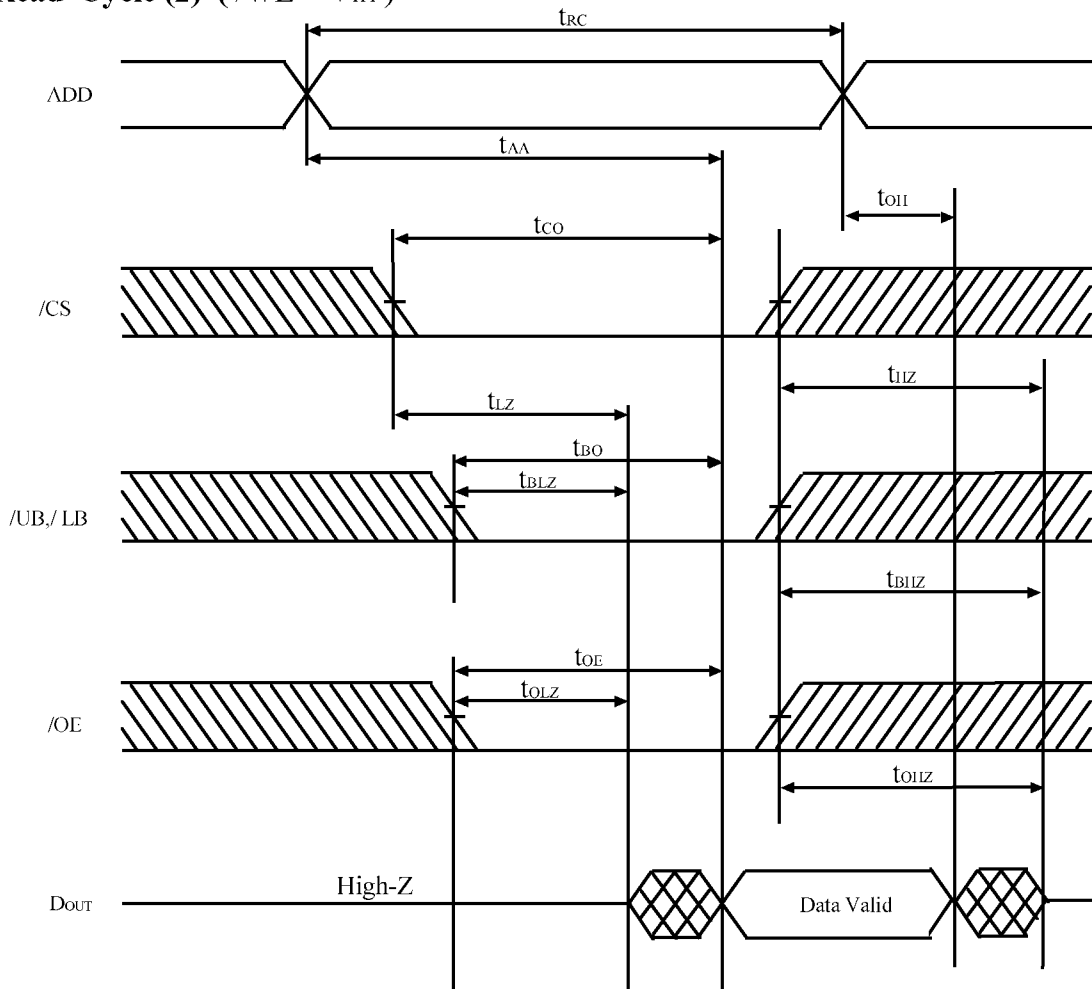
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Timing Waveforms

Read Cycle (1) ($/CS = /OE = V_{IL}$, $/WE = V_{IH}$, $/UB$ and, or $/LB = V_{IL}$)

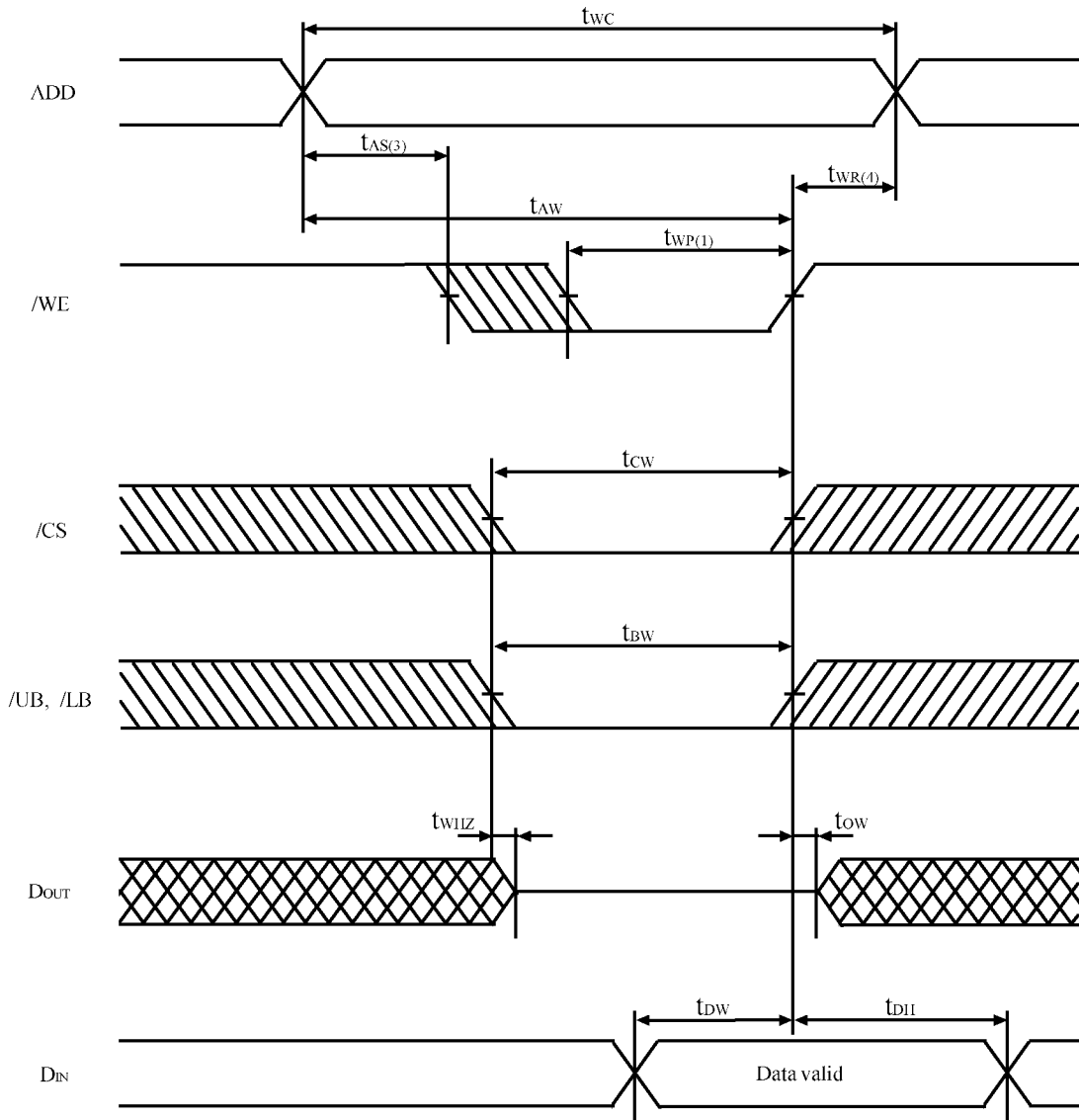


Read Cycle (2) ($/WE = V_{IH}$)



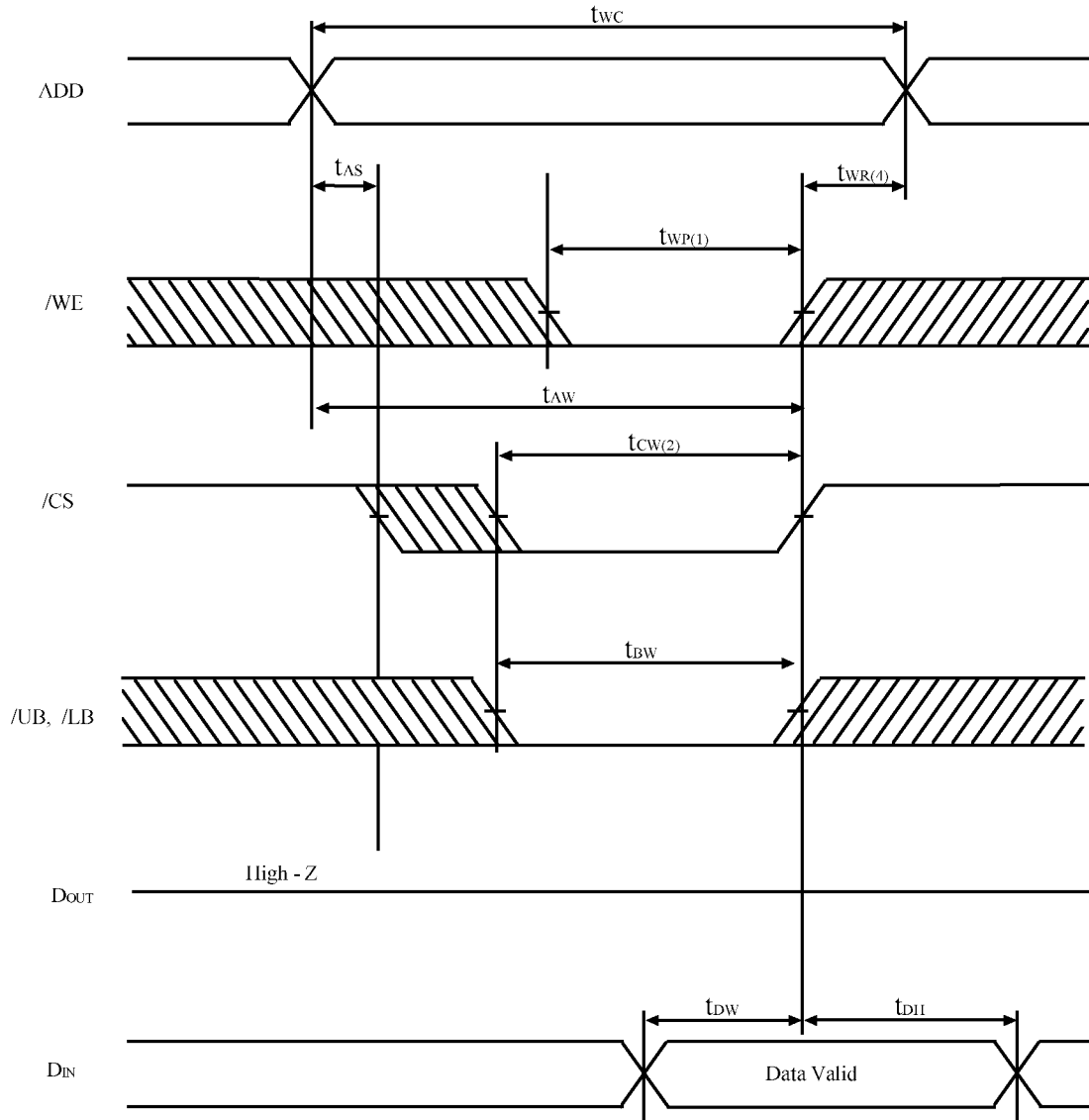
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Write Cycle (1) (/WE Controlled)



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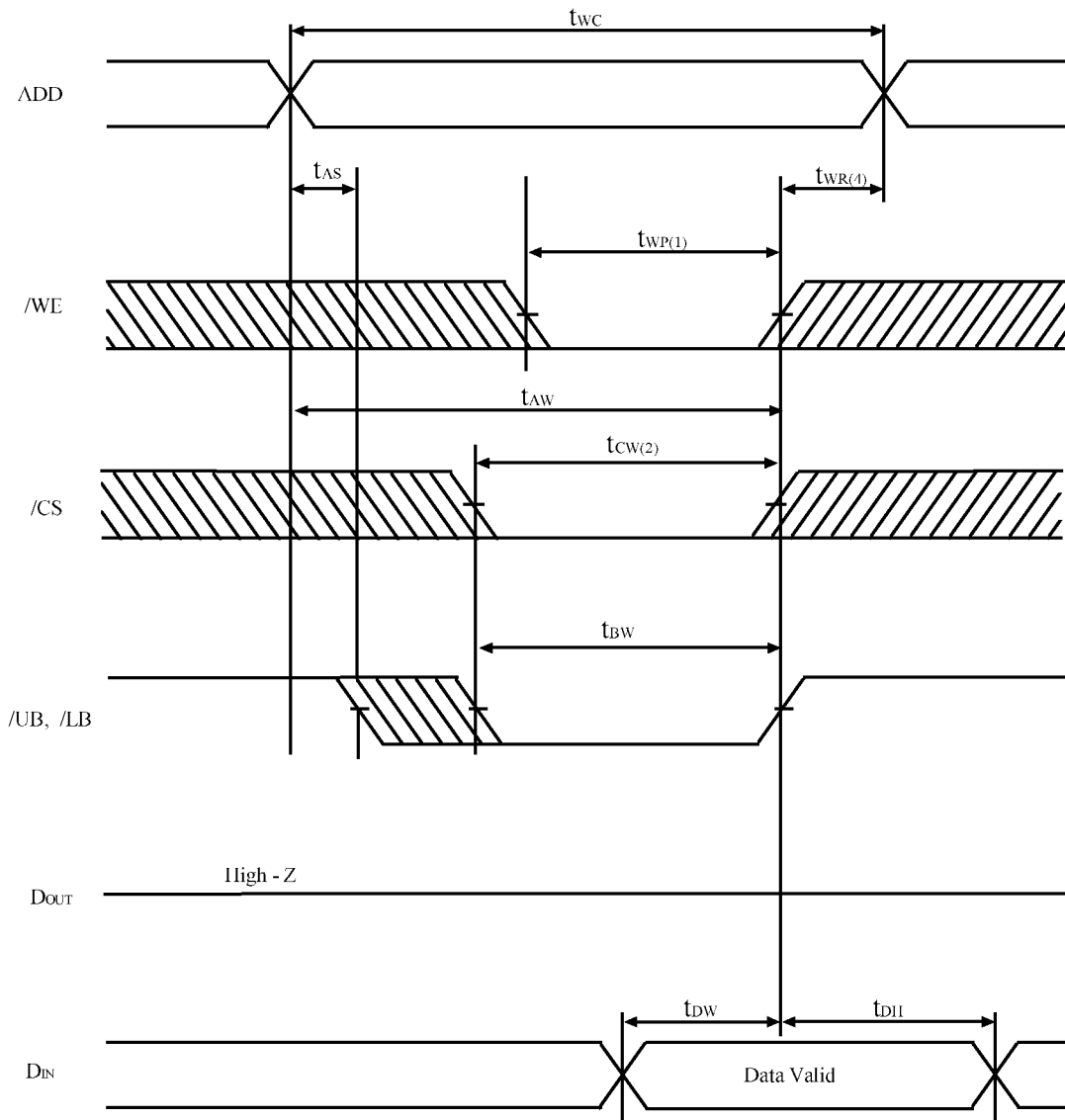
Write Cycle (2) (/CS Controlled)



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Write Cycle (3) (/UB, /LB Controlled)



Notes (Write Cycle):

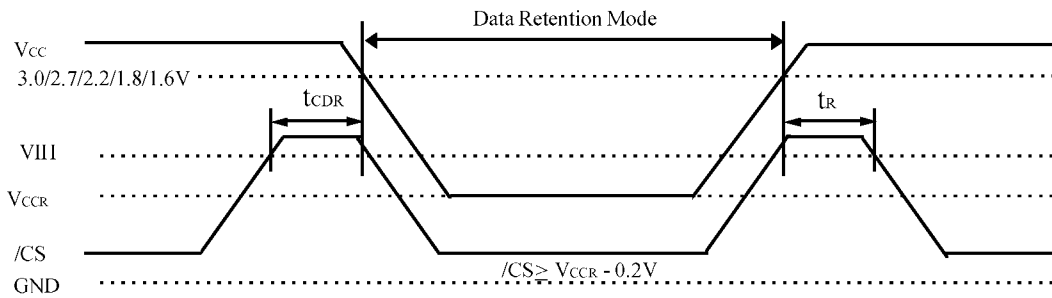
1. A write occurs during the overlap(t_{WP}) of a low /CS and low /WE. A write begins at the latest transition among /CS going low and /WE going low : A write end at the earliest transition among /CS going high and /WE going high, t_{WP} is measured from the beginning of write to the end of write.
2. t_{CW} is measured from the later of /CS going low to end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as /CS, or /WE, or /UB, or /LB going high.

PRELIMINARY
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Data Retention Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
V _{CCR}	Data Retention Supply Voltage	1.5	-	3.6	V
I _{CCR}	Data Retention Current	LL- Version SL - Version	-	5 1	uA
t _{CDR}	Chip Select to Data Retention Time	0	-	-	ms
t _R	Operation Recovery Time	5	-	-	ms

Data Retention Timing



Note: When retaining data in standby mode, supply voltage can be lowered within a certain range.
 Read or write cycle cannot be performed while the supply voltage is low.

PRELIMINARY
GM76FV1664, GM76FU1664, GM76FQ1664, GM76FE1664, GM76FS1664

Package Dimensions

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